

REMARKS

Claims 1-8 and 12-16 are pending and rejected. Applicant traverses the rejections.

Claim 2 was rejected under 35 USC 112 as being indefinite. Claim 2 has been amended to better claim the subject matter. This amendment is supported by Fig. 24 and paragraph [0132] of the specification. As an example, conducting structures 1103 is coupled to 1107, which in turn is coupled to 1106, which in turn is coupled to 1108, which in turn is coupled to 1105. Thus the first micro bump is connected not only to an associated opposite first landing pad, but to a second landing pad.

Claims 1-8 and 12-16 were rejected under 35 USC 102 as being anticipated by Yamagishi (US App 2004/0239349), Moro (US App 2002/0088977), Winer (USP 6,525,922), and Berlin (USP 6,104, 082). Yamagishi in FIG. 1A shows that a micro-bump 103A is coupled to an opposing landing pad on the integrated circuit package 104. Mori in FIG. 11 shows that a micro-bump 58 is coupled to an opposing landing pad on the integrated circuit package 64. Winer in FIG. 1 shows that a micro-bump 20 is coupled to an opposing landing pad on the integrated circuit package 16. Berlin in FIG. 2b shows that a micro-bump 62 is coupled to an opposing landing pad on the integrated circuit package 68, where the micro-bump is slightly offset from the landing pad (not labeled, but coupled to second micro-bump 69). Thus all four references cited by the Examiner either directly or indirectly disclose that the micro-bump of the array of micro-bumps disposed on the surface of the IC die in a first pattern are connected to their opposing landing pad of the array of landing pads disposed on the inside surface of the IC package in a second pattern.

Claim 1 has among other features an interposing structure disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package, the interposer coupling a first micro-bump in a first position in the array of micro-bumps to a first landing pad located opposite to the first position and to a second landing pad in the array of landing pads. None of the four references cited by the Examiner either disclose or suggest the first micro-bump be coupled to both a first and second landing pad. Thus this claim should be allowable.

Claims 2-8 being dependent upon claim 1 should be allowable for at least the reason claim 1 is allowable.

Claim 12 has among other features means for coupling a first micro-bump in a first position in the array of micro-bumps to a first landing pad disposed opposite the first position and to a second landing pad located in a different position in the array of landing pads, the means being disposed inside the integrated circuit package between the integrated circuit die and the inside surface of the integrated circuit package. None of the four references cited by the Examiner either disclose or suggest the first micro-bump be coupled to both a first and second landing pad. Thus this claim should be allowable.

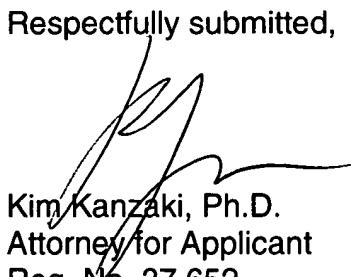
Claims 13-16 being dependent upon claim 12 should be allowable for at least the reason claim 12 is allowable.

CONCLUSION

All claims should be now be in condition for allowance and a Notice of Allowance is respectfully requested.

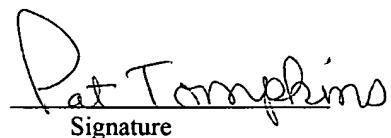
If there are any questions, the applicant's attorney can be reached at Tel: 408-879-6149 (Pacific Standard Time).

Respectfully submitted,


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I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on December 29, 2005.

Pat Tompkins
Name


Signature